

DERWENT- 1993-071210
ACC-NO:

DERWENT- 199309
WEEK:

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TITLE: Cheap and safe etching soln. for polyamide resin - contains water, aprotic e.g. THF and protic e.g. ethanol organic solvents miscible with water and basic cpds. e.g. sodium hydroxide

PATENT-ASSIGNEE: NISSHIN FLOUR MILLING CO[NISS]

PRIORITY-DATA: 1991JP-0172719 (July 12, 1991)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 05017604 A	January 26, 1993	N/A	005	C08J 007/02

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 05017604A	N/A	1991JP-0172719	July 12, 1991

INT-CL (IPC): C08J007/02, C08L079:08, C09K013/06, H01L021/308

ABSTRACTED-PUB-NO: JP 05017604A

BASIC-ABSTRACT:

Soln. contains water, (A) aprotic organic solvents miscible with water, (B) protic organic solvents miscible with water and (C) basic cpds.

(A) is pref. at least one selected from ketone, ether and amide solvents, partic. e.g. methyl ethyl ketone, THF, dioxane or N-methylpyrrolidone. (B) is pref. at least one selected from alcohol, glycol and glycol ether solvents, partic. e.g. methanol or ethanol. (C) is pref. at least one selected from alkali metal hydroxides and quat. ammonium hydroxides, partic. e.g. NaOH or KOH. The contents of (A), (B) and (C) are pref. 5 to 85 wt.%, 5 to 85 wt.% and 0.5 to 30 wt.%, respectively, based on the soln.

ADVANTAGE - The soln. is cheap, safe and easy to handle and can etch completely cured polyamide resin quick

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: CHEAP SAFE ETCH SOLUTION POLYAMIDE RESIN CONTAIN WATER
APROTIC THF PROTIC ETHANOL ORGANIC SOLVENT MISCIBLE WATER
BASIC COMPOUND SODIUM HYDROXIDE

DERWENT-CLASS: A23 A35 E19 L03 U11

CPI-CODES: A05-F01D; A11-C04D; E07-A04; E07-D03; E10-E04J; E10-E04L; E10-E04M3;
E32-A04; E33-A03; L04-C07C;

EPI-CODES: U11-A10;

CHEMICAL-CODES: Chemical Indexing M3 *01* Fragmentation Code F000 F113 M280 M320 M413
M510 M521 M530 M540 M782 M903 M904 M910 Q454 Q615 R023 Specific
Compounds 00895M

Chemical Indexing M3 *02* Fragmentation Code F000 F163 M280 M320 M413
M510 M521 M530 M540 M782 M903 M904 Q454 Q615 R023 Ring Index 00261
00262 00263 Specific Compounds 01057M 12337M 13444M

Chemical Indexing M3 *03* Fragmentation Code F011 F012 F423 H181 H2 H211 J5
J521 L9 L941 M210 M211 M273 M281 M320 M413 M510 M521 M530 M540
M782 M903 M904 Q454 Q615 R023 Specific Compounds 05268M

Chemical Indexing M3 *04* Fragmentation Code H5 H581 H582 H583 H584 H589
H8 M210 M211 M212 M213 M214 M215 M216 M220 M221 M222 M223 M224
M225 M226 M231 M232 M233 M272 M282 M312 M320 M321 M322 M323 M332
M342 M383 M391 M392 M393 M416 M620 M782 M903 M904 Q454 Q615 R023
Specific Compounds 90113M 90114M

Chemical Indexing M3 *05* Fragmentation Code J0 J011 J3 J371 M210 M211 M212
M213 M214 M215 M216 M220 M221 M222 M223 M224 M225 M226 M231 M232
M233 M262 M281 M320 M416 M620 M782 M903 M904 Q454 Q615 R023 Specific
Compounds 90094M

Chemical Indexing M3 *06* Fragmentation Code A100 A111 A119 A940 C108
C500 C550 C730 C801 C802 C803 C804 C805 C807 M411 M782 M903 M904 Q454
R023 Markush Compounds 199309-D6701-M

Chemical Indexing M3 *07* Fragmentation Code H4 H401 H481 H8 M210 M211
M212 M213 M214 M215 M216 M220 M221 M222 M223 M224 M225 M226 M231
M232 M233 M272 M281 M320 M416 M620 M782 M903 M904 Q454 Q615 R023
Markush Compounds 199309-D6702-M

Chemical Indexing M3 *08* Fragmentation Code J5 J581 M210 M211 M212 M213

M214 M215 M216 M220 M221 M222 M223 M224 M225 M226 M231 M232 M233
M262 M282 M320 M416 M620 M782 M903 M904 Q454 Q615 R023 Markush
Compounds 199309-D6703-M

UNLINKED-DERWENT-REGISTRY-NUMBERS: ; 0895U

POLYMER-MULTIPUNCH-CODES-AND-KEY-SERIALS:

Key Serials: 0229 1283 2020 2483 2500 2578 3000

Multipunch Codes: 014 03- 11& 141 231 466 470 473 575 583

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1993-031831

Non-CPI Secondary Accession Numbers: N1993-054418